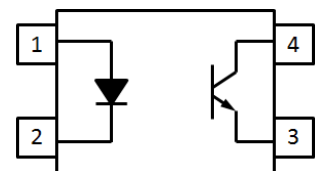


### 4 PIN SOP PHOTOTRANSISTOR PHOTOCOUPLER EL357NU-G Series

Preliminary



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

#### Features:

- Halogens free  
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- Compliance with EU REACH
- Pb free and RoHS compliant
- Current transfer ratio  
(CTR: 100~400% at  $I_F = 0.5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- Operating temperature  $-40^\circ\text{C} \sim 125^\circ\text{C}$
- High isolation voltage between input and output ( $V_{iso} = 3750\text{ V rms}$ )
- UL and cUL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

#### Description

The EL357NU-G series contains an infrared emitting diode, optically coupled to a phototransistor detector.

The devices in a 4-pin small outline SMD package.

#### Applications

- DC-DC Converters
- Programmable controllers
- Telecommunication equipments
- Signal transmission between circuits of different potentials and impedances

### Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	$I_F$	50	mA
	Peak forward current (1us, pulse)	$I_{FP}$	1	A
	Reverse voltage	$V_R$	6	V
	Power dissipation	$P_D$	70	mW
Output	Power dissipation	$P_C$	150	mW
	Collector current	$I_C$	30	mA
	Collector-Emitter voltage	$V_{CEO}$	60	V
	Emitter-Collector voltage	$V_{ECO}$	5	V
Total Power Dissipation		$P_{TOT}$	200	mW
Isolation Voltage*1		$V_{ISO}$	3750	V rms
Operating temperature		$T_{OPR}$	-40 ~ +125	°C
Storage temperature		$T_{STG}$	-40 ~ +150	°C
Soldering Temperature*2		$T_{SOL}$	260	°C

#### Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*2 For 10 seconds

## Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

### Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	$V_F$	-	1.3	1.6	V	$I_F = 1\text{mA}$
Reverse current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 6\text{V}$
Input capacitance	$C_{in}$	-	30	250	pF	$V = 0, f = 1\text{kHz}$

### Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	$I_{CEO}$	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	$BV_{CEO}$	60	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	$BV_{ECO}$	5	-	-	V	$I_E = 0.01\text{mA}$

## Transfer Characteristics (Ta=25°C unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL357NU	50	-	600	%	$I_F = 0.5\text{mA}, V_{CE} = 5\text{V}$
	EL357NUA	100	-	200		
	EL357NUB	150	-	300		
	EL357NUC	200	-	400		
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-		0.35	V	$I_F = 3\text{mA}, I_C = 1.6\text{mA}$
Isolation resistance	$R_{IO}$	$5 \times 10^{10}$	-	-	$\Omega$	$V_{IO} = 500\text{Vdc}, 40\sim 60\% \text{ R.H.}$
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Turn-on time	$t_{on}$	-	1	-	$\mu\text{s}$	$V_{CC} = 5\text{V}, I_F = 16\text{mA}, R_L = 1.9\text{K}\Omega$
Turn-off time	$t_{off}$	-	50	-		

\* Typical values at  $T_a = 25^\circ\text{C}$

## Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

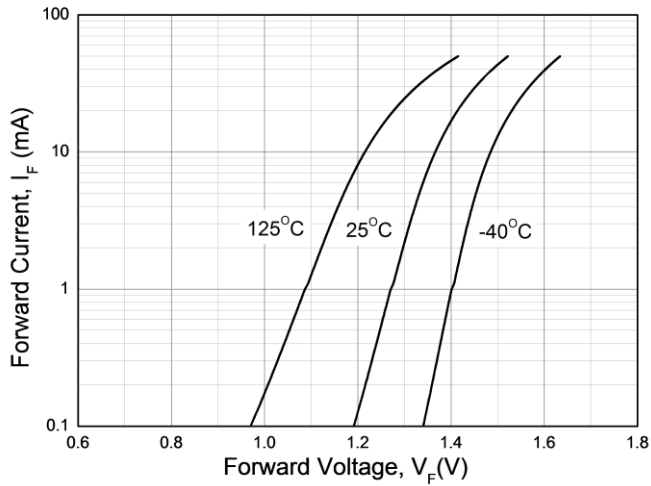


Figure 2. Collector Current vs. Forward Current

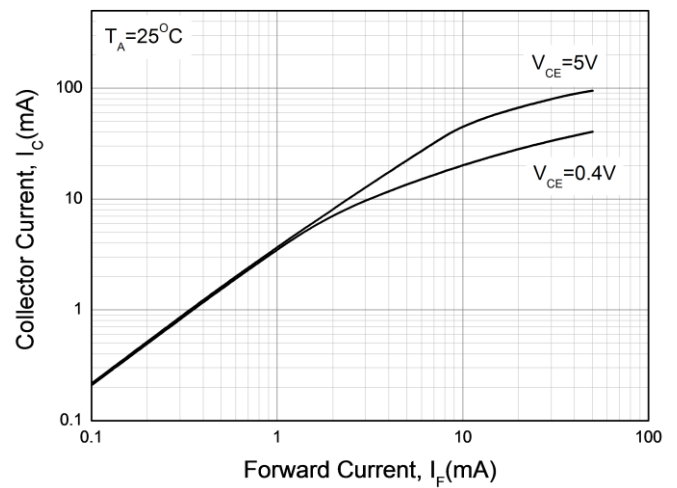


Figure 3. Normalized Current Transfer Ratio vs. Forward Current

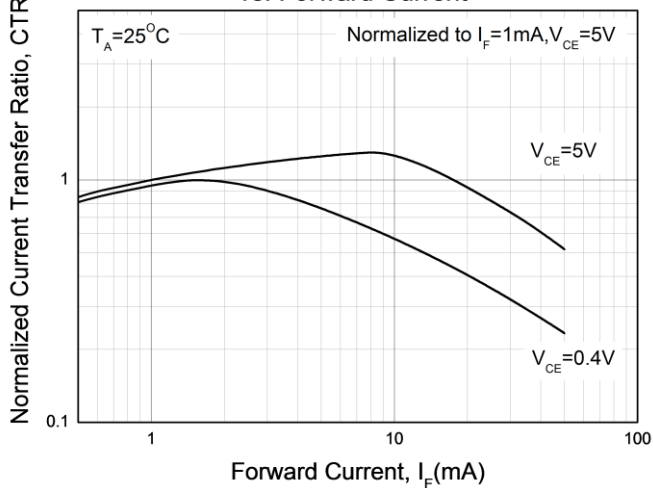


Figure 4. Collector Current vs. Collector Emitter Voltage

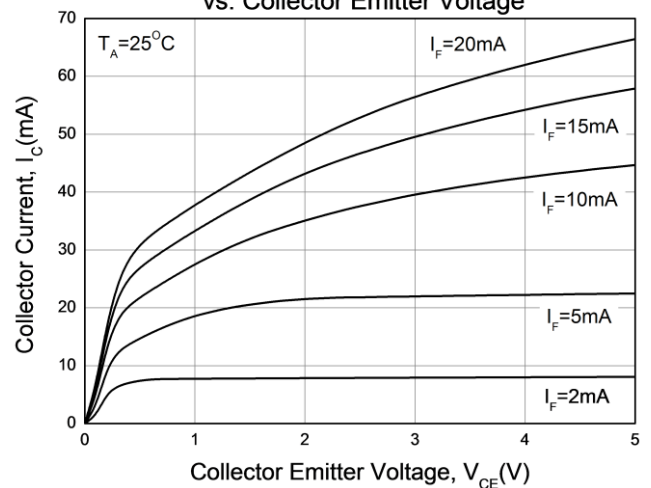


Figure 5. Collector Current vs. Collector Emitter Voltage

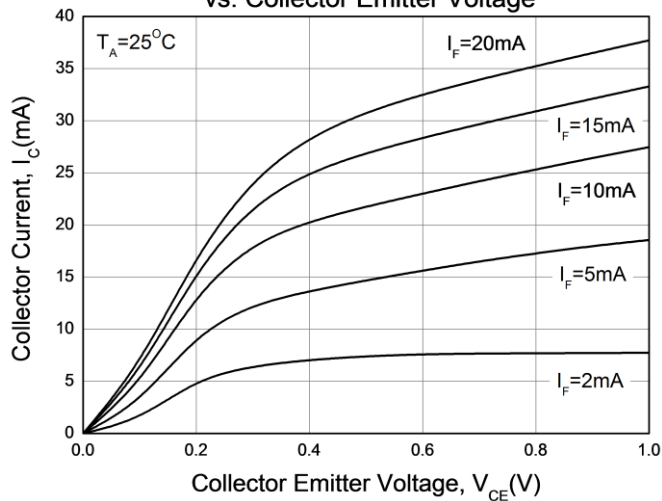


Figure 6. Collector Current vs. Ambient Temperature

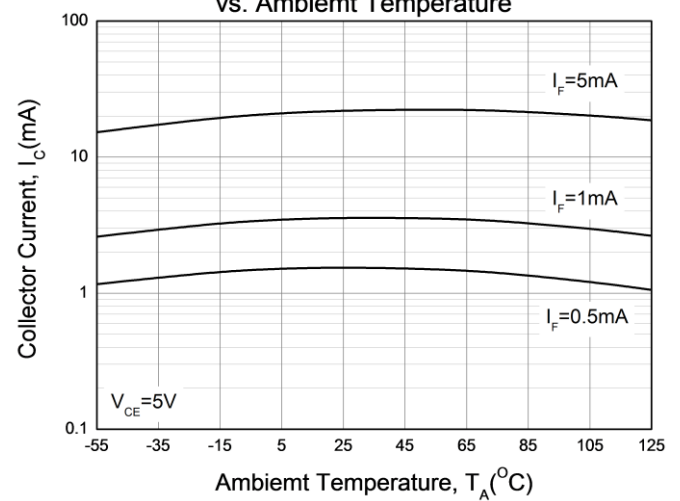


Figure 7. Current Transfer Ratio vs. Ambient Temperature

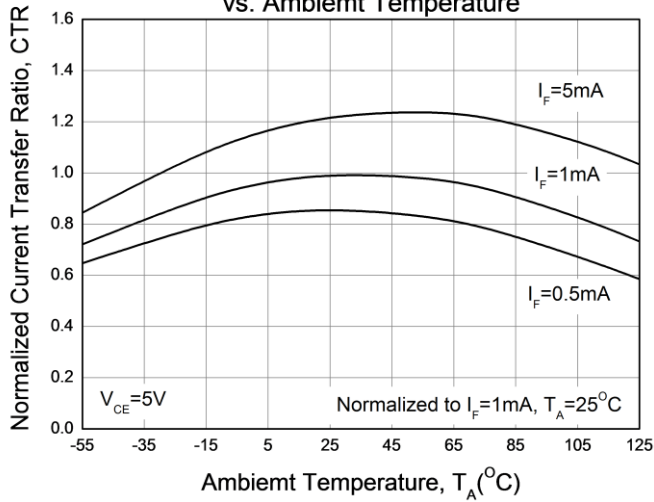


Figure 8. Collector Dark Current vs. Ambient Temperature

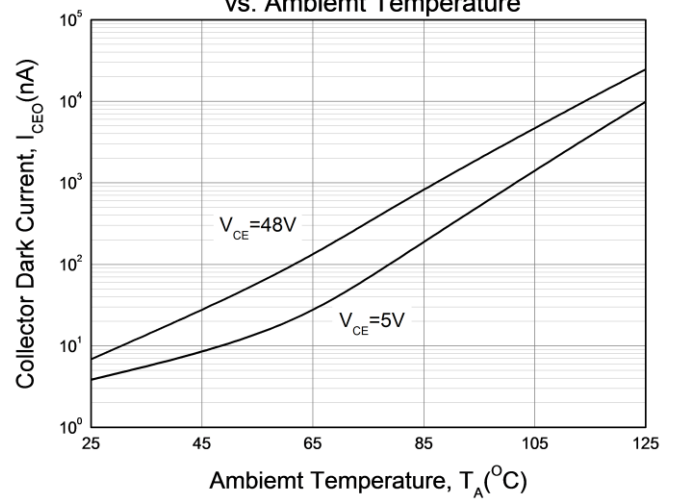


Figure 9. Switching Speed vs. Load resistance

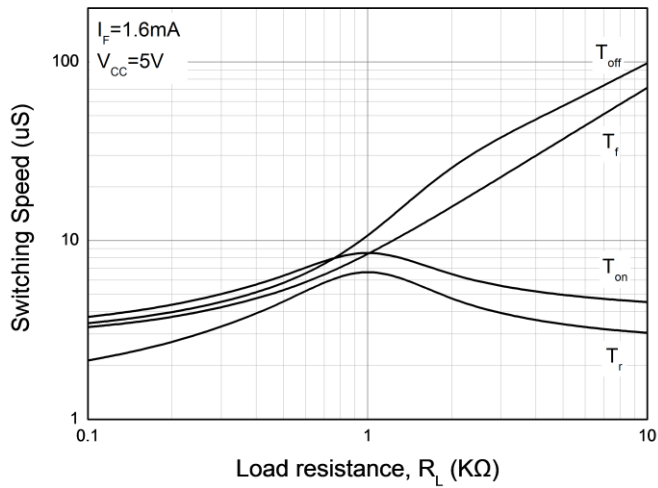


Figure 10. Collector-Emitter Saturation Voltage vs. Ambient Temperature

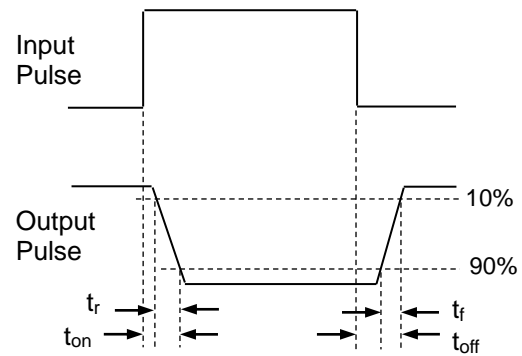
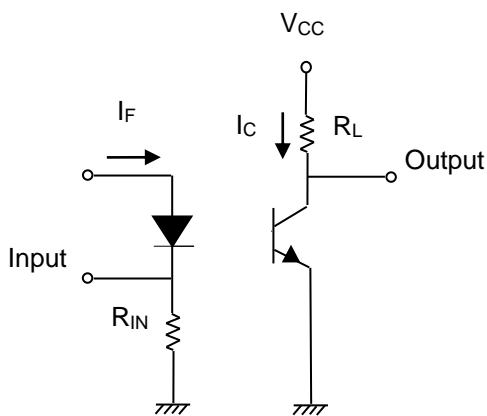
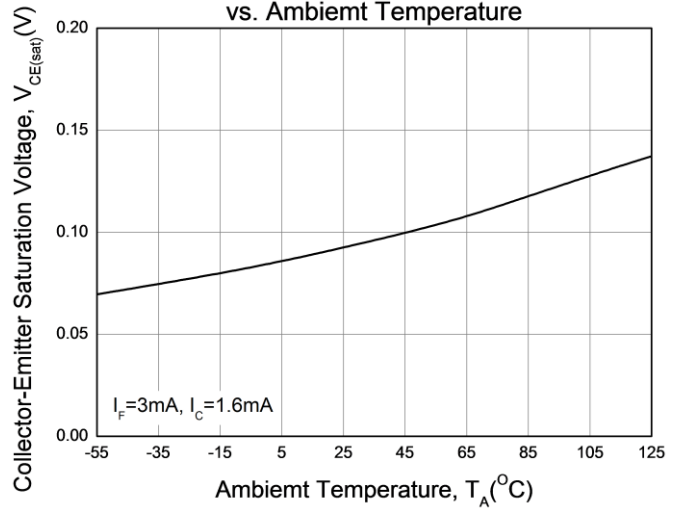


Figure 11. Switching Time Test Circuit & Waveforms

## Order Information

### Part Number

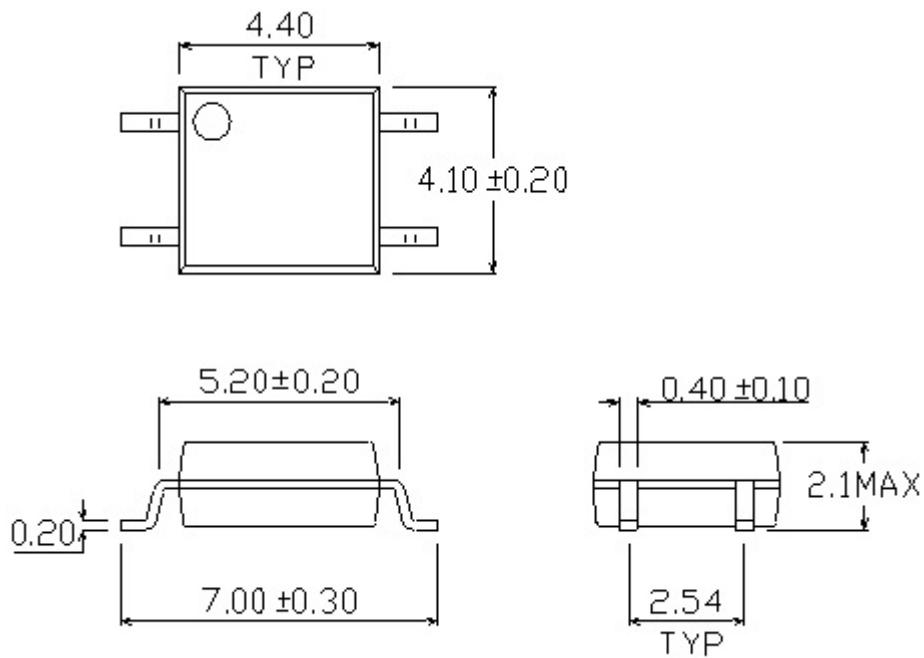
**EL357NU(X)(Y)-VG**

#### Notes

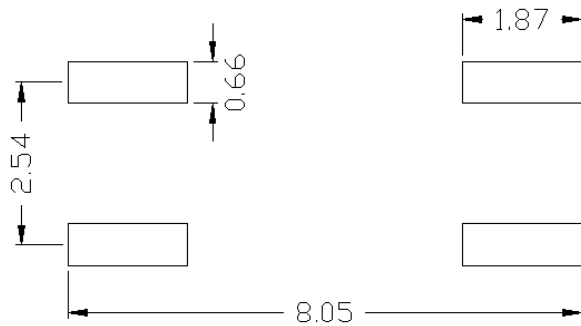
X = CTR Rank (A, B, C or none)  
Y = Tape and reel option (TA, TB or none).  
V = VDE (optional)  
G = Halogens free

Option	Description	Packing quantity
None	Standard SMD option	100 units per tube
-V	Standard SMD option + VDE	100 units per tube
(TA)	TA Tape & reel option	3000 units per reel
(TB)	TB Tape & reel option	3000 units per reel
(TA)-V	TA Tape & reel option + VDE	3000 units per reel
(TB)-V	TB Tape & reel option + VDE	3000 units per reel

**Package Dimension (Dimensions in mm)**



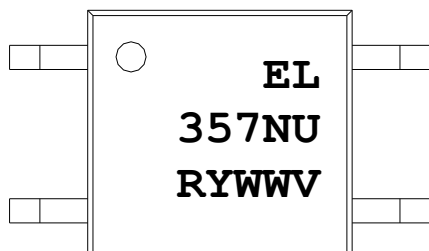
**Recommended pad layout for surface mount leadform**



**Notes**

Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

## Device Marking

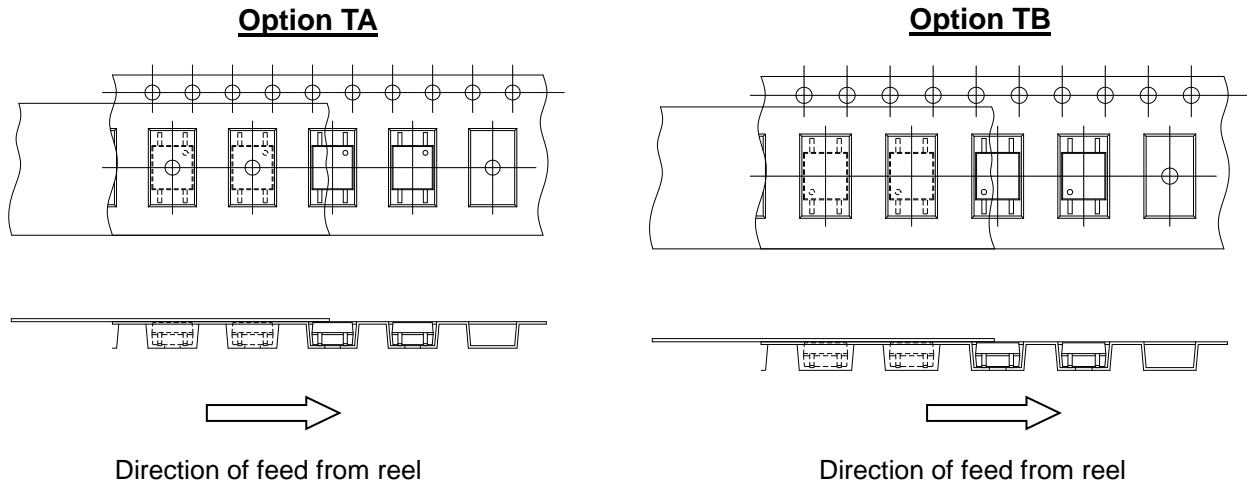


### Notes

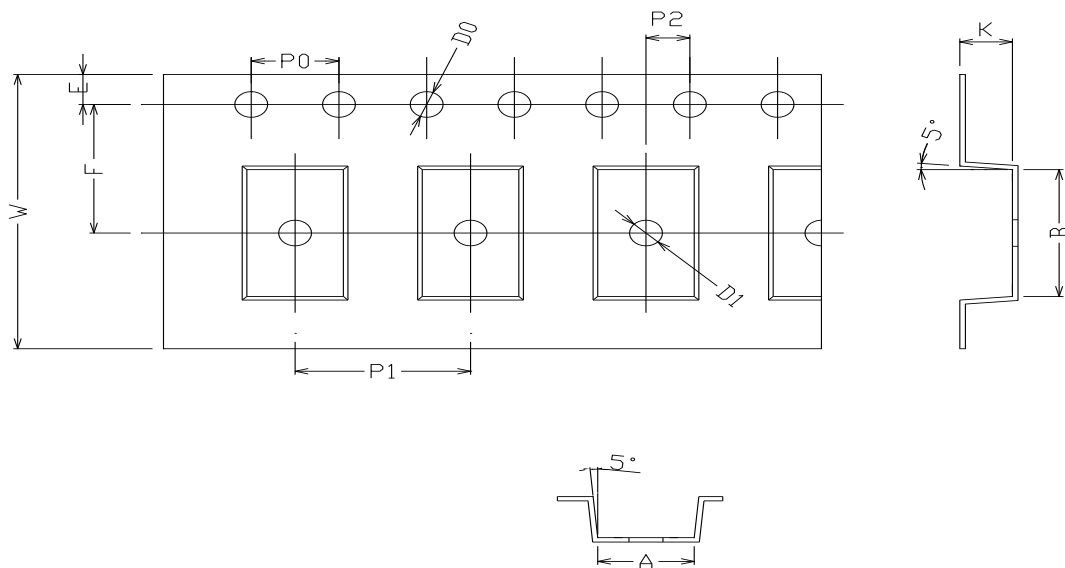
EL	denotes XI BNANG 357
NU	denotes Device Number
R	denotes CTR Rank (A, B, C or none)
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)



## Tape & Reel Packing Specifications



## Tape dimensions

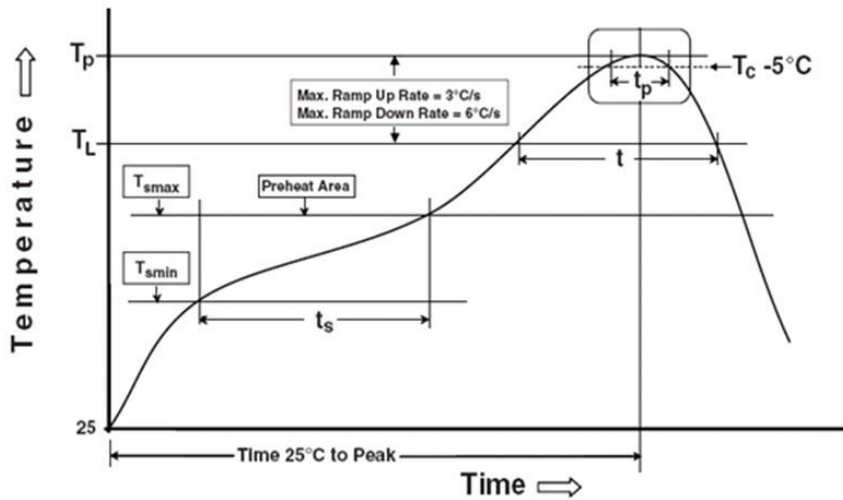


Dimension No.	A	B	Do	D1	E	F
Dimension (mm)	$4.4 \pm 0.1$	$7.6 \pm 0.1$	$1.5 + 0.1/-0$	$1.5 \pm 0.1$	$1.75 \pm 0.1$	$7.5 \pm 0.05$
Dimension No.	Po	P1	P2	t	W	K
Dimension (mm)	$4.0 \pm 0.05$	$8.0 \pm 0.1$	$2.0 \pm 0.1$	$0.3 \pm 0.03$	$16.0 \pm 0.2$	$2.4 \pm 0.1$

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_P$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_P$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_P - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

## DISCLAIMER

1. Above specification may be changed without notice. XI BNANG will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. XI BNANG assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
4. These specification sheets include materials protected under copyright of XI BNANG. Reproduction in any form is prohibited without the specific consent of XI BNANG.
5. This product is not intended to be used for military , aircraft , automotive , medical , life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized XI BNANG sales agent for special application request.
6. Statements regarding the suitability of products for certain types of applications are based on XI BNANG 's knowledge of typical requirements that are often placed on XI BNANG products in generic applications. Such statements are not binding statements about the suitability of products for a particular application . It is the customer 's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application . Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time . All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts . Product specifications do not expand or otherwise modify XI BNANG 's terms and conditions of purchase, including but not limited to the warranty expressed therein.